CLAIMS

1. A semiconductor package comprising:

a semiconductor device with one or more device-side electrodes being formed on a circuit-bearing surface; and

a flexible substrate having a patterned wiring and a thermoplastic insulating layer formed on either or both sides of the patterned wiring, the flexible substrate being bent around said semiconductor device, wherein:

said flexible substrate has a first electrode provided on said semiconductor device-side surface of said flexible substrate, the first electrode being connected to said device-side electrode of said semiconductor device and sealed by said thermoplastic insulating layer, and a second electrode provided on a surface different from the surface on which said first electrode is provided; and

said flexible substrate has at least two or more layers of patterned wiring formed thereon.

2. The semiconductor package according to claim 1, wherein

said flexible substrate has a groove or a portion having less number of wiring layers formed at a bend of said flexible substrate or on a region including the bent.

3. The semiconductor package according to claim 2, wherein

said flexible substrate has a cavity formed on said flexible substrate so as to accommodate said semiconductor device in said cavity portion.

4. The semiconductor package according to claim 2, wherein

said flexible substrate includes portions where the

flexible substrate is bent and which are directly adhered to each other.

5. The semiconductor package according to claim 1, wherein said flexible substrate has a cavity formed on said flexible substrate so as to accommodate said semiconductor device in said cavity portion.

6. A semiconductor package comprising:

a semiconductor device with one or more device-side electrodes being formed on a circuit-bearing surface; and

a flexible substrate having a patterned wiring and a thermoplastic insulating layer formed on either or both sides of the patterned wiring, said flexible substrate being bent around said semiconductor device, wherein:

said flexible substrate has a first electrode provided on said semiconductor device-side surface of the flexible substrate, said first electrode being connected to the device-side electrode of said semiconductor device and sealed by said thermoplastic insulating layer, and a second electrode provided on a surface different from the surface on which said first electrode is provided; and

said flexible substrate includes portions where the flexible substrate is bent and which are directly adhered to each other.

7. The semiconductor package according to claim 6, wherein the semiconductor device is accommodated in a recessed portion created by said flexible substrate being bent and directly adhered to each other.

8. A stacked semiconductor package wherein

a plurality of semiconductor packages of the same type or different types according to any one of claims 1 to 7 are electrically connected via said electrodes and three-dimensionally stacked in layers.